CLAIMS

1. A composition for an encapsulant film, the composition comprising an ethylene/alpha-olefin copolymer satisfying the following conditions (a) to (d):

(a) a density is 0.85 to 0.89 g/cc;

(b) a molecular weight distribution is 1.8 to 2.3;

(c) a melt index (MI, 190°C, 2.16 kg load conditions) is 1 to 100 dg/min; and

(d) a full width at half maximum (FWHM) of a crystallization peak shown during measuring a crystallization temperature by cross-fractionation chromatography (CFC) is 15 to 50,

wherein the alpha-olefin is comprised in 10 to 50 mol% with respect to the copolymer, and

wherein the alpha-olefin comprises one or more selected from the group consisting of propylene, 1-butene, 1-pentene, 4-methyl-1-pentene, 1-hexene, 1-heptene, 1-octene, 1-decene, 1-undecene, 1-dodecene, 1-tetradecene, 1-hexadecene and 1-eicosene.

2. The composition for an encapsulant film according to claim 1, wherein the melt index is 2 to 20 dg/min.

3. The composition for an encapsulant film according to claim 1, wherein the full width at half maximum of the crystallization peak is 16 to 50.

4. The composition for an encapsulant film according to claim 1, wherein a melting temperature of the ethylene/alpha-olefin copolymer is 70°C or less.

5. The composition for an encapsulant film according to claim 1, wherein a weight average molecular weight (Mw) of the ethylene/alpha-olefin copolymer is 40,000 to 150,000 g/mol.

6. The composition for an encapsulant film according to claim 1, wherein the ethylene/alpha-olefin copolymer has a melt flow rate ratio (MFRR, $MI_{10}/MI_{2.16}$) which is a value of a melt index (MI_{10}, 190°C, 10 kg load conditions) with respect to a melt index($MI_{2.16}$, 190°C, 2.16 kg load conditions) of 8.0 or less.

7. The composition for an encapsulant film according to claim 1, wherein a crystallization temperature of the ethylene/alpha-olefin copolymer is 70°C or less.

8. The composition for an encapsulant film according to claim 1, further comprising one or more selected from the group consisting of an unsaturated silane compound, an amino silane compound, a crosslinking agent, a crosslinking auxiliary agent, a light stabilizer, a UV absorbent and a thermal stabilizer.

9. An encapsulant film comprising the composition for an encapsulant film according to any one of claims 1 to 8.

10. A solar cell module comprising the encapsulant film of claim 9.